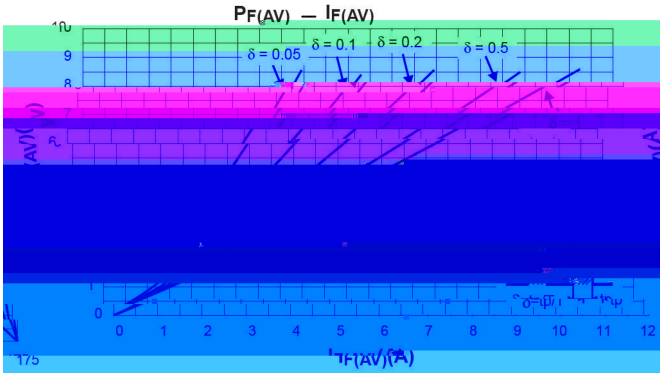
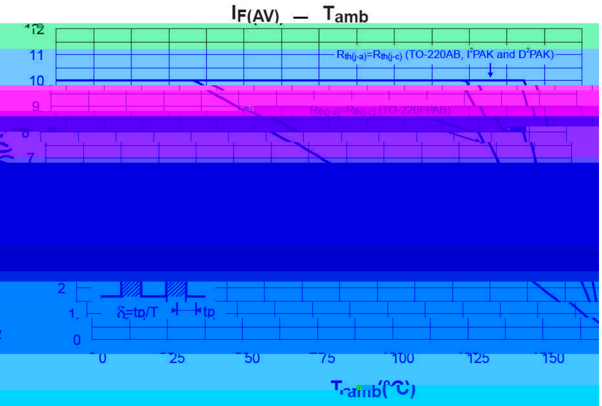
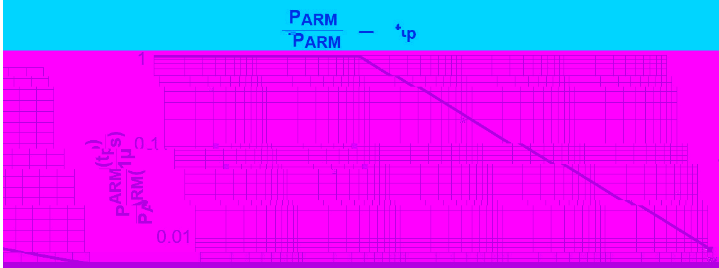
Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	150	V
RMS Forward Current	$I_{F(RMS)}$	30	A
Average Forward Current	$I_{F(AV)}$	10	A
Average Forward Current	$I_{F(AV)}$ total device	20	A
Non Repetitive Peak Surge Current	I_{FSM}	180	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	1.5	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

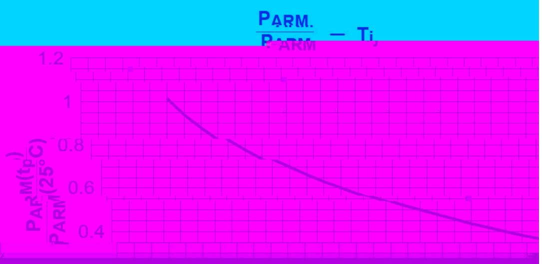
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	I_F =10A(Tc=25)			0.9	V
		I_F =10A(Tc=125)		0.69	0.75	V
		I_F =20A(Tc=25)			1.0	V
		I_F =20A(Tc=125)		0.79	0.86	V

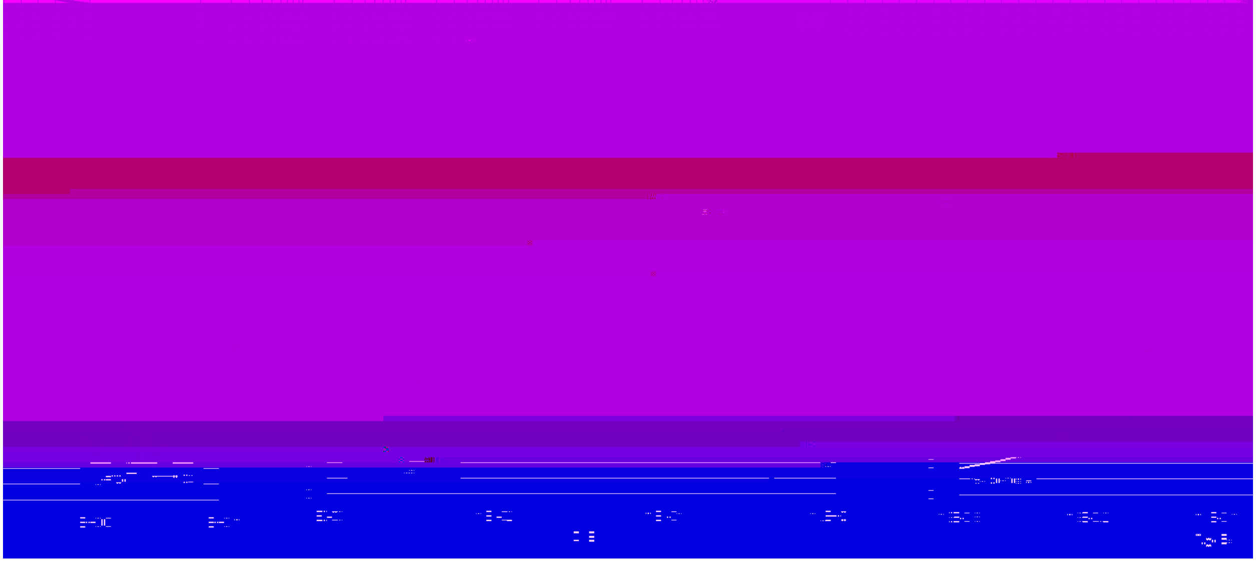
/ Electrical Characteristic Curve



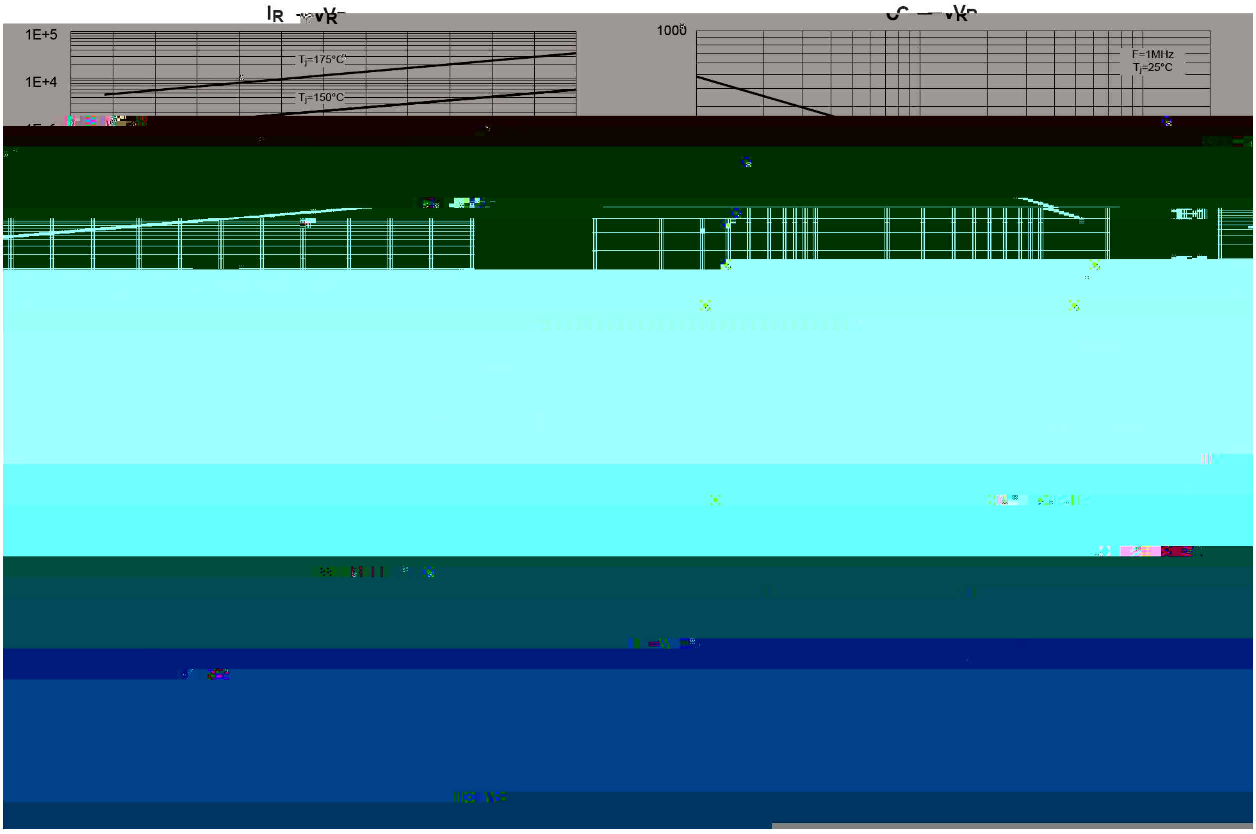




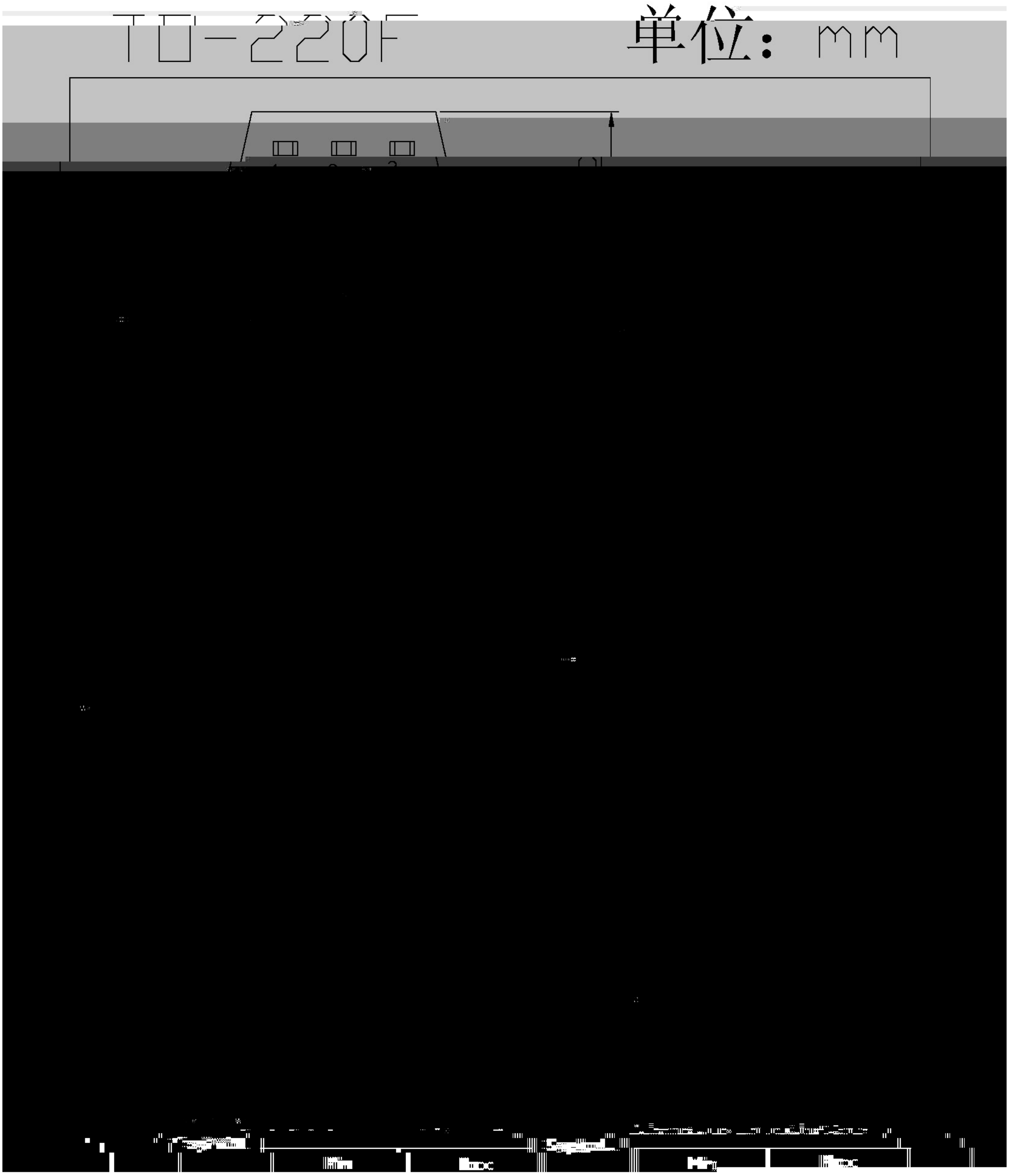




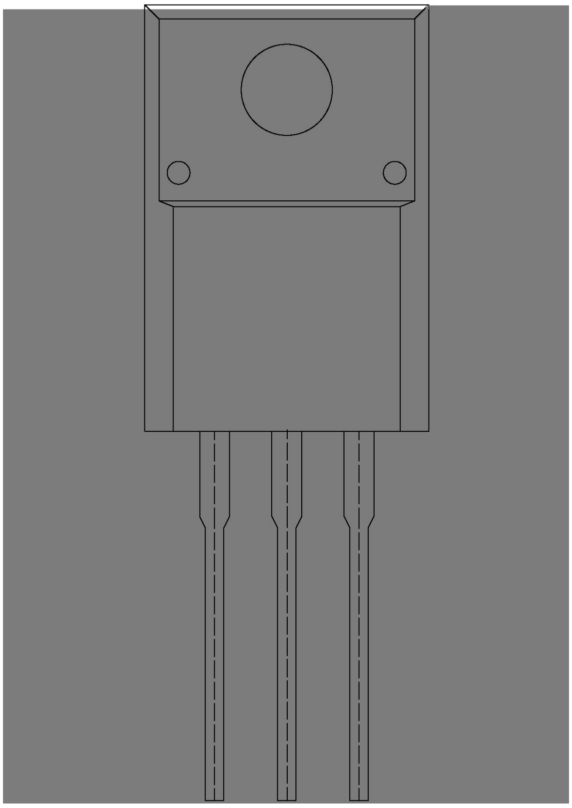
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

MBRF20150

CT:

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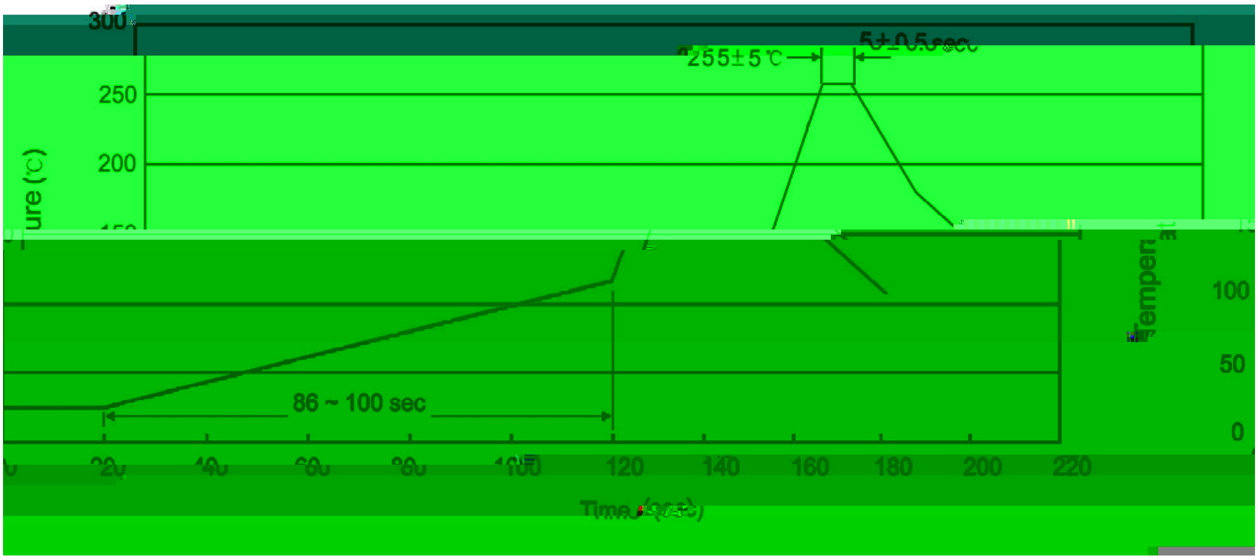
Note:

BR: Company Code

MBRF20150: Pr57d05ba6C t , code change with Lot No. 9 TD3.2410 Tc8( )Tj

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

1 25 150 60 90sec; 1.Preheating:25~150 , Time:60~90sec.

2 255±5 5±0.5sec; 2.Peak Temp.:255±5 , Duration:5±0.5sec.

3 2 10 /sec. 3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units	Dimension (unit mm^3)